

1 2 3 4 5 6 7 8

REV	MODIFICATION	DATE	DRAW
A4	Release To ECN20130516	2013.05.31	Michelle
A5	Release To ECN20150607	2015.06.18	Michelle
B0	Release To ECN20160103	20160112	Michelle



RoHS Compliant

Specification

- 1.Current Rating:2A AC/DC
- 2.Voltage Rating:250V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:1000MΩ Min.
- 5.Dielectric Withstanding Voltage:AC800V/Minute
- 6.Operating Temperature:-25°C~+85°C

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Contact Pin:Copper Alloy SQ. Pin 0.50mm

Finish:

- 1.Housing:See P/N Option
- 2.Contact Pin:See P/N Option

Part No.:AD05800 XX X X 5 2

No. Of Pin
04~40

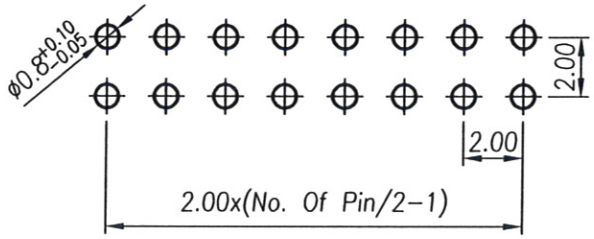
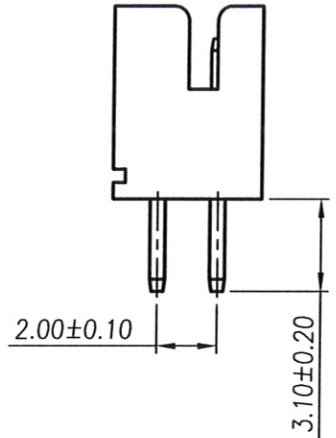
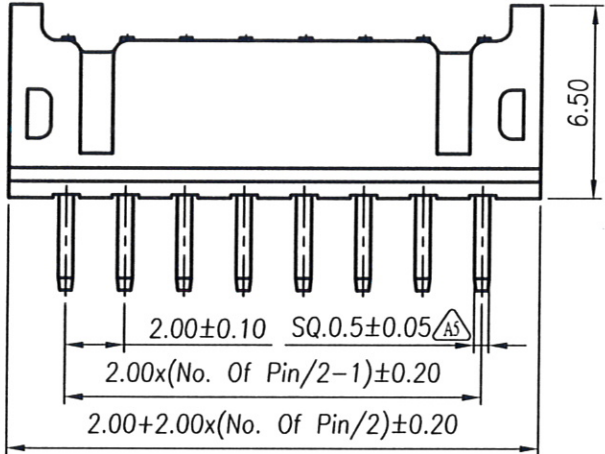
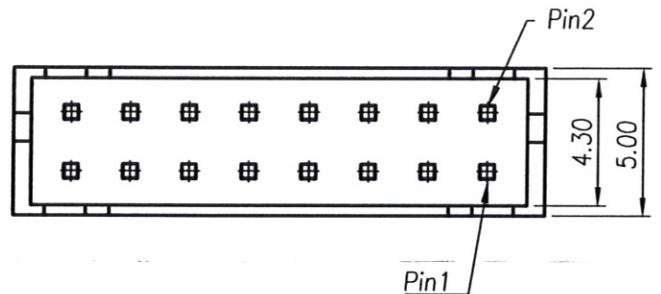
Packing
5:Bag

Housing Material

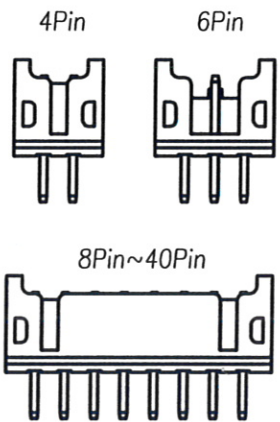
- 4:Nylon66+Glass Fiber
- UL94V-0 Natural
- A:Nylon66+Glass Fiber
- UL94V-0 Black


Plating

- 1:Bright Tin Plated Over Nickel
- 2:Matte Tin Plated Over Nickel
- 3:Gold Plated Over Nickel




RECOMMENDED P.C.B LAYOUT





金上達科技股份有限公司

GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 2.00mm 180' DIP Dual Row	
.x± 0.35	.x'± 2'	APR. C.F. Liao 20160112	PART NO. AD05800XXXX52	DWG NO. AD05800XXXX52
.xx± 0.25	.x'± 1'	CHK. Abel 20160112	UNITS: mm CUSTOMER DRAWING	
.xxx± 0.15	.xx'± 0.5'	DRAW. Michelle 20160112	SIZE: A4	SCALE 4:1 SHEET 1 / 1 REV B0 V

A
B
C
D
E
F

A
B
C
D
E
F

1 2 3 4 5 6 7 8